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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: : Harry Michael Siegel et al.
Application No. : 10/062,595
Filed : January 31, 2002
For : SYSTEM AND METHOD FOR ALIGNING AN
INTEGRATED CIRCUIT DIE ON AN INTEGRATED
CIRCUIT SUBSTRATE
Group No. : 3725
Examiner : David B. Jones

MAIL STOP ISSUE FEE

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

Sir:

The undersigned hereby certifies that the following documents:

1. Amendment Under 37 C.F.R. § 1.312;
2. One (1) sheet of Replacement drawing;
3. Redline copy of drawing; and
4. A postcard receipt

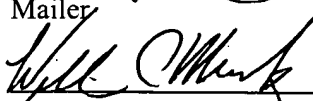
relating to the above application, were deposited as "First Class Mail" with the United States Postal Service, addressed to Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on July 18, 2005.

Date: July 18, 2005

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